



Material Content Data Sheet



Sales Product Name		ICE1HS01G		Issued		27. May 2015		
MA#		MA000711866						
Package		PG-DSO-8-41		Weight*		81.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.020	3.72	3.72	37218	37218
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.673	0.83		8294	
wire	non noble metal	copper	7440-50-8	27.330	33.68	34.56	336780	345593
	noble metal	gold	7440-57-5	0.116	0.14	0.14	1432	1432
	encapsulation	organic material	carbon black	1333-86-4	0.143	0.18		1758
plastics	plastics	epoxy resin	-	4.613	5.68		56843	
		silicondioxide	60676-86-0	42.800	52.75	58.61	527408	586009
leadfinish	non noble metal	tin	7440-31-5	0.814	1.00	1.00	10029	10029
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1104	1104
glue	plastics	acrylic resin	-	0.302	0.37		3723	
		noble metal	silver	7440-22-4	1.209	1.49	1.86	14892
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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